

## CMOS 8-bit Single Chip Microcomputer

Piggyback/  
evaluator type**Description**

The CXP81900M is a CMOS 8-bit single chip micro-computer of piggyback/evaluator combined type, which is developed for evaluating the function of the CXP81952M/81960M.

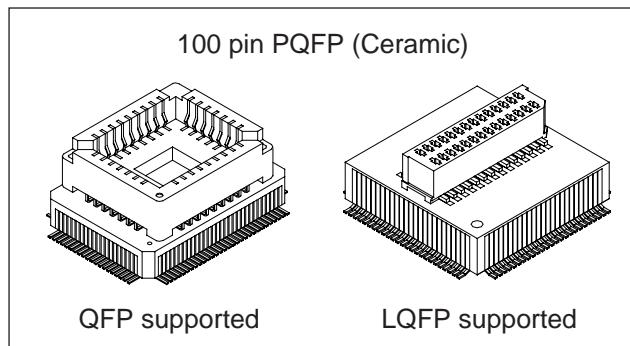
**Features**

- A wide instruction set (213 instructions) which cover various types of data.
  - 16-bit operation/multiplication and division/boolean bit operation instructions
- Minimum instruction cycle
  - 250ns at 16MHz operation (4.5 to 5.5V)
  - 333ns at 12MHz operation (2.7 to 5.5V)
  - 122 $\mu$ s at 32kHz operation
- Applicable EPROM
  - LCC type 27C256, LCC type 27C512  
(Maximum 60Kbytes are available.)
- Incorporated RAM capacity
  - 2048 bytes
- Peripheral functions
  - A/D converter
    - 8-bit, 12-channel, successive approximation method  
(Conversion time of 20 $\mu$ s/16MHz)
  - Serial interface
    - Incorporated buffer RAM  
(Auto transfer for 1 to 32 bytes), 1 channel
    - Incorporated 8-bit and 8-stage FIFO  
(Auto transfer for 1 to 8 bytes), 1 channel
  - Timer
    - 8-bit timer, 8-bit timer/counter
    - 19-bit time base timer
    - 32kHz timer/counter
  - High precision timing pattern generator
    - PPG 19-pin, 32-stage programmable
    - RTG 5 pins, 2 channels
  - PWM/DA gate output
    - PWM output 12 bits, 2 channels  
(Repetitive frequency 62.5kHz/16MHz)
    - DA gate pulse output 13 bits, 4channels
  - FRC capture unit
  - PWM output
  - Remote control receiving circuit
  - General purpose prescaler
  - HSYNC counter
- Interruption
- Standby mode
- Package
  - 100-pin ceramic PQFP

Note) Mask option depends on the type of the CXP81900M. Refer to the Products List for details.

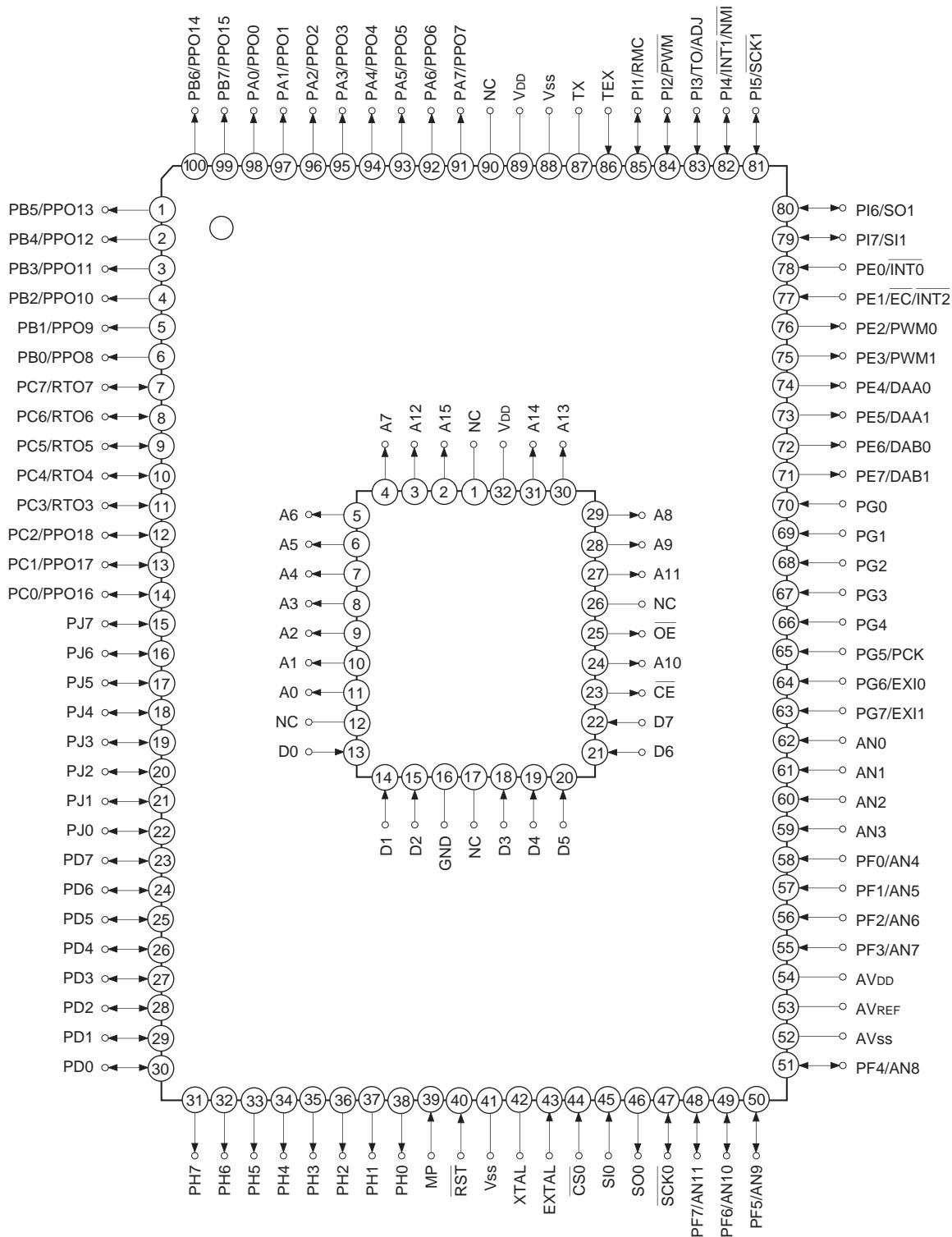
**Structure**

Silicon gate CMOS IC



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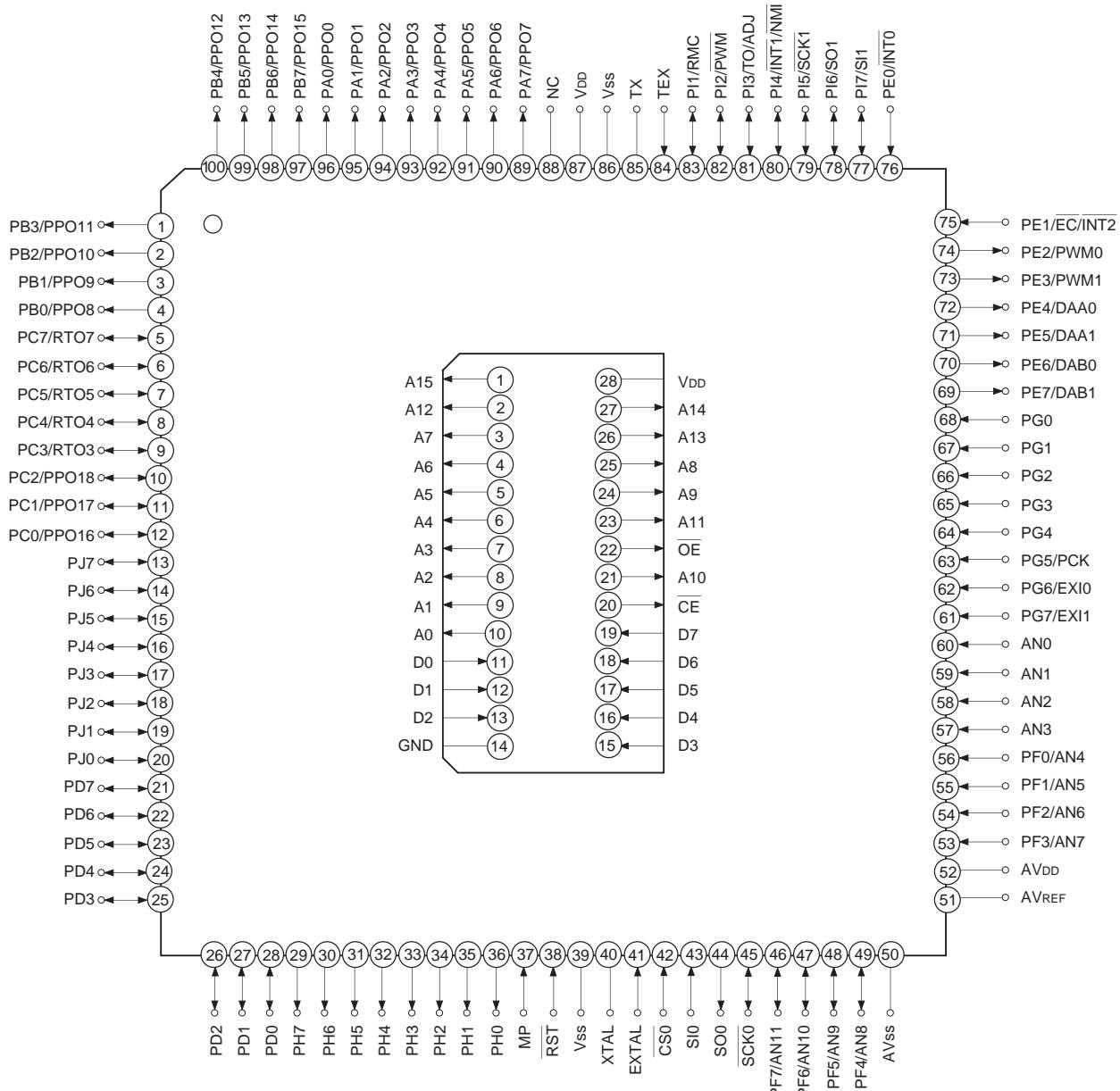
### Pin Assignment in Piggyback Mode (QFP package)



**Note)**

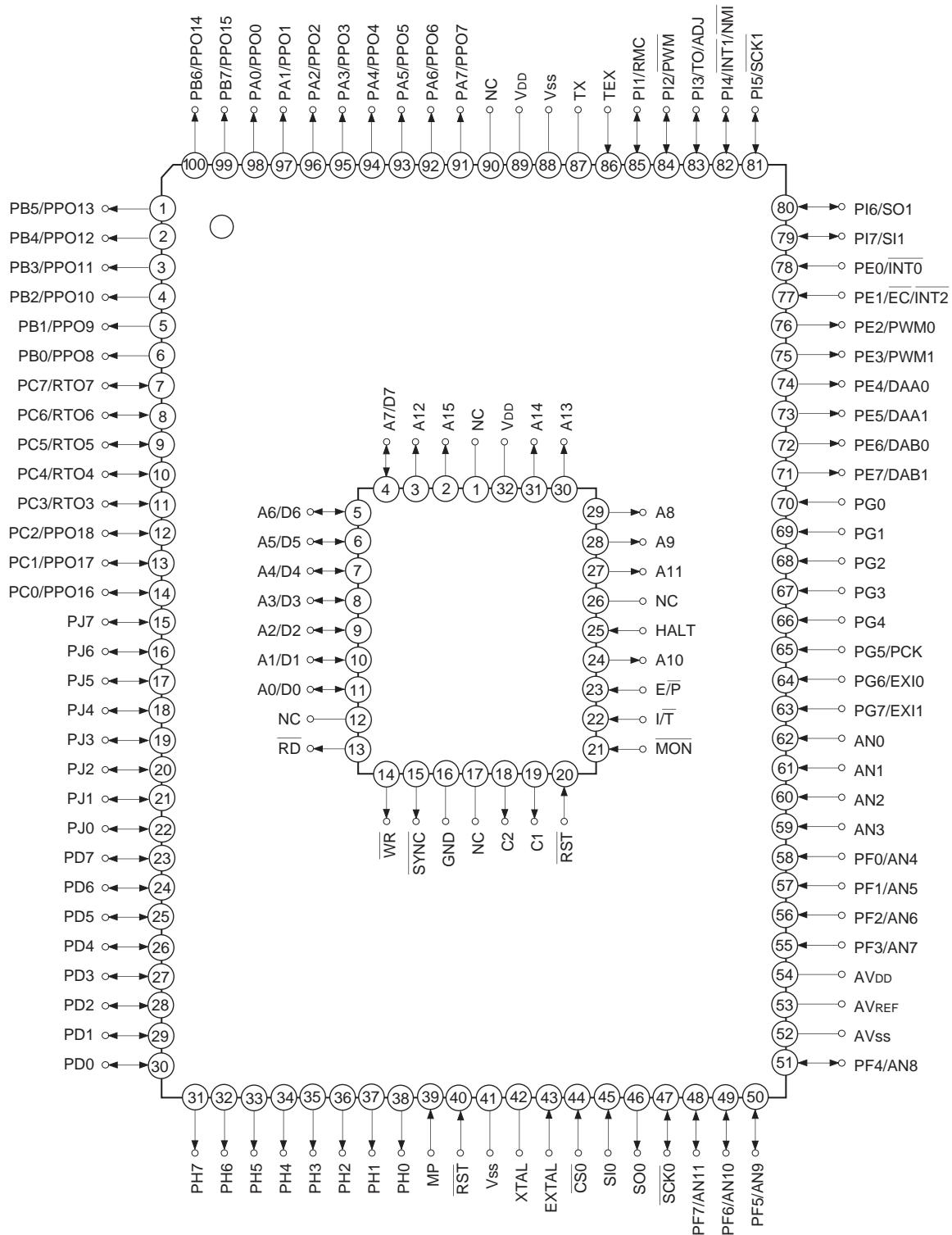
1. NC (Pin 90) is always connected to VDD.
2. Vss (Pins 41 and 88) are both connected to GND.
3. MP (Pin 39) is always connected to GND.

### Pin Assignment in Piggyback Mode (LQFP package)



- Note)**
1. NC (Pin 88) is always connected to Vdd.
  2. Vss (Pins 39 and 86) are both connected to GND.
  3. MP (Pin 37) is always connected to GND.

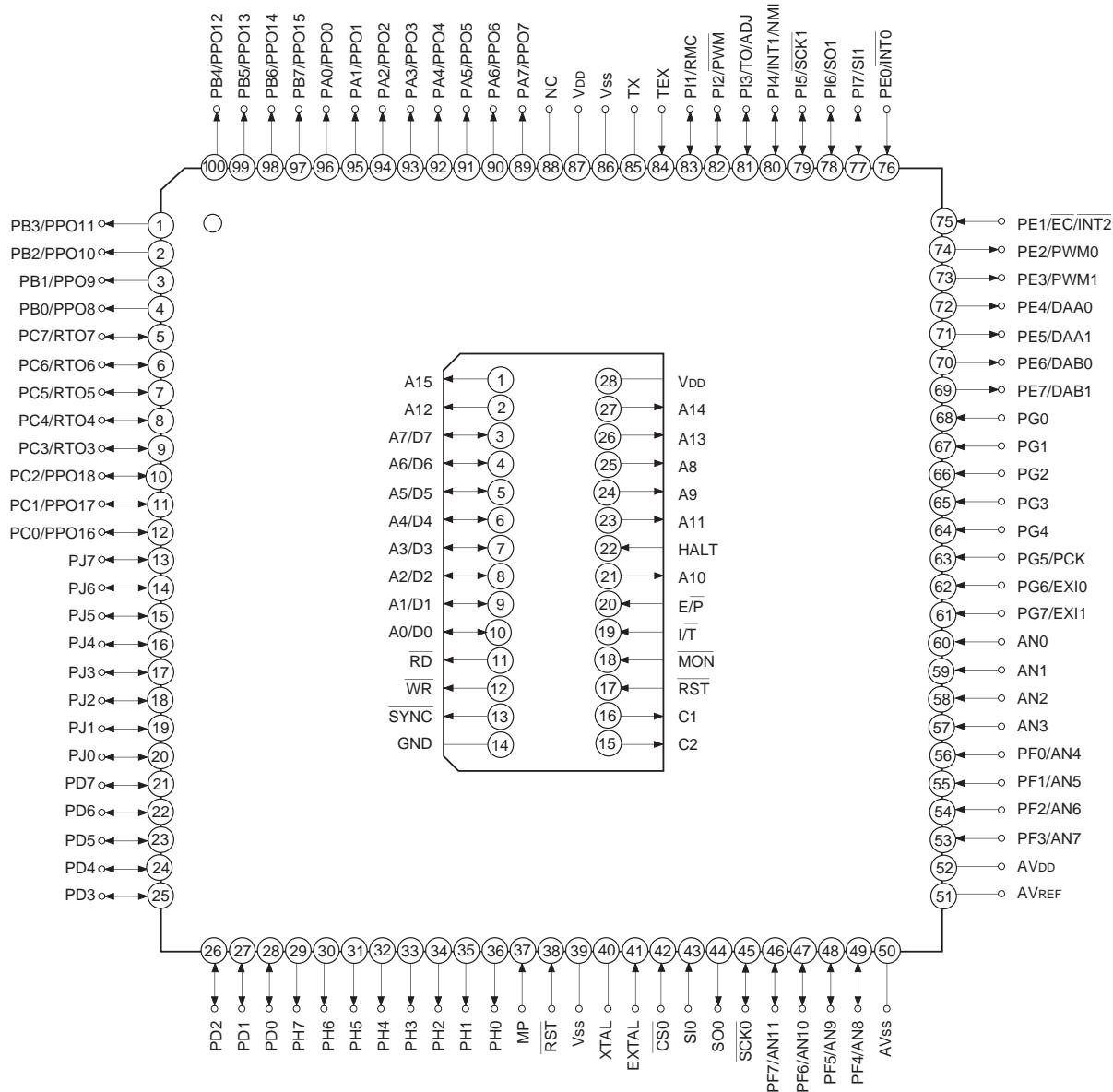
### Pin Assignment in Evaluator Mode (QFP package)



**Note)**

1. NC (Pin 90) is always connected to VDD.
2. Vss (Pins 41 and 88) are both connected to GND.
3. MP (Pin 39) is always connected to GND.

### Pin Assignment in Evaluator Mode (LQFP package)



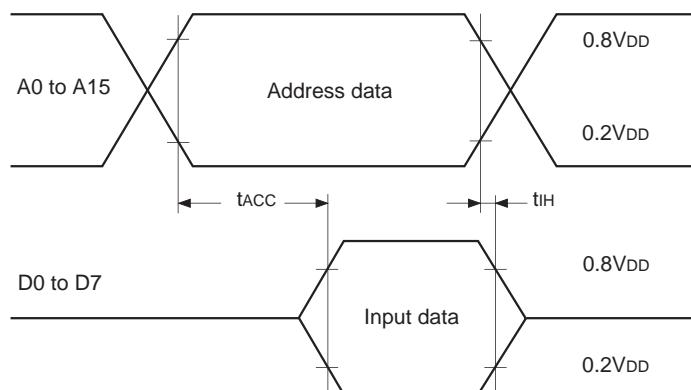
- Note)**
1. NC (Pin 88) is always connected to VDD.
  2. Vss (Pins 39 and 86) are both connected to GND.
  3. MP (Pin 37) is always connected to GND.

**EPROM Read Timing (Ta = -20 to +75°C, VDD = 2.7 to 5.5V, Vss = 0V)**

Item	Symbol	Pin	Min.	Max.	Unit
Address → data input delay time	tACC	A0 to A15		100 <sup>*1</sup>	ns
		D0 to D7		75 <sup>*2</sup>	
Address → data hold time	tIH	A0 to A15 D0 to D7	0		ns

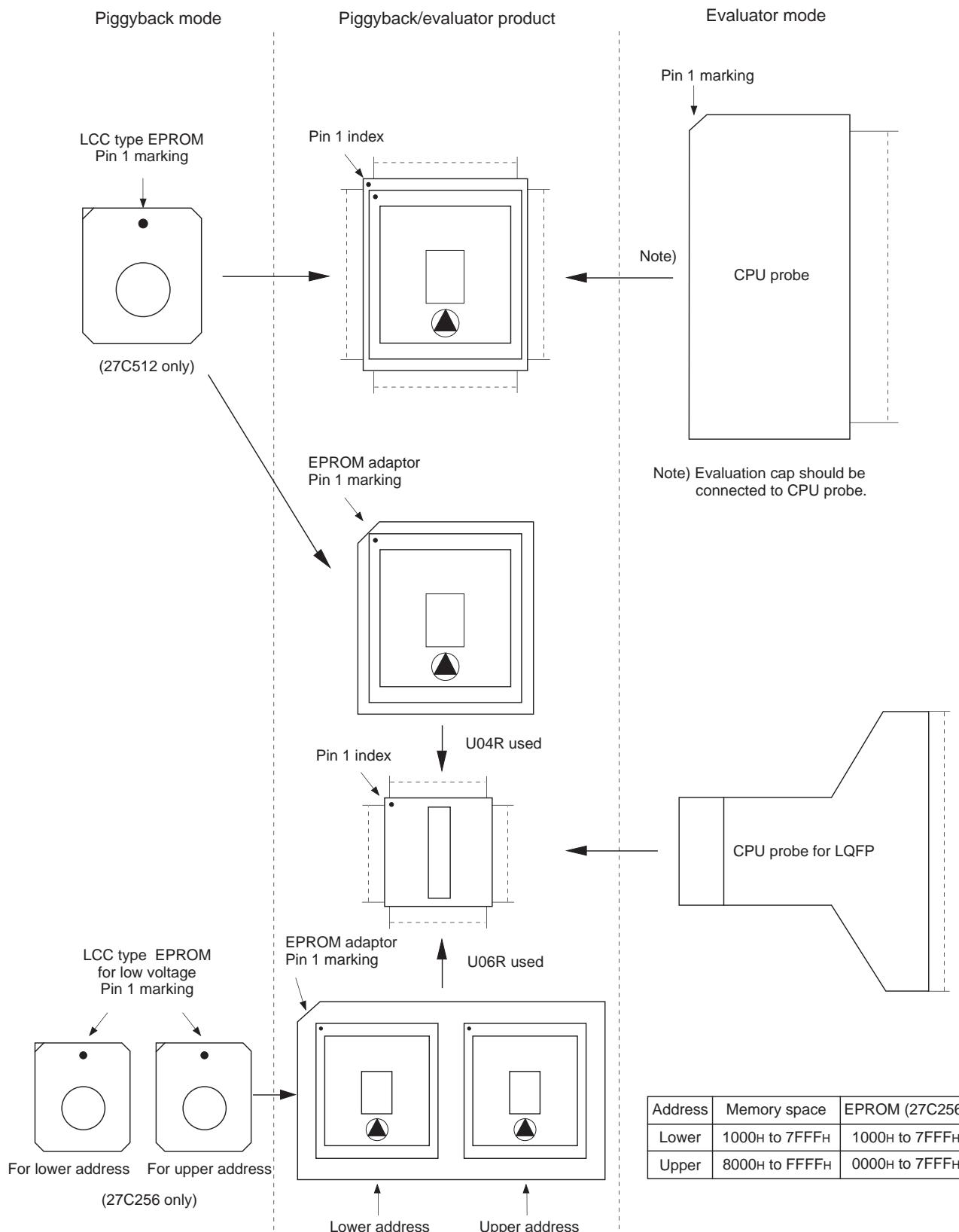
\*1 At 12MHz operation (VDD = 4.5 to 5.5V)

\*2 At 12MHz operation (VDD = 2.7 to 5.5V), At 16MHz operation (VDD = 4.5 to 5.5V)

**Products List**

Option item	Products			
	Mask product		Piggyback/evaluator product	
	CXP81952M	CXP81960M	CXP81900M-U04Q	CXP81900M-U06R
Package	100-pin plastic QFP/LQFP		100-pin ceramic PQFP	
ROM capacity	52Kbytes	60Kbytes	EPROM 60Kbytes	
			27C512 × 1	27C256 × 2
Pull-up resistor for reset pin	Existent/Non-existent		Existent	
Supply voltage	2.7 to 5.5V		2.7 to 5.5V	2.7 to 5.5V

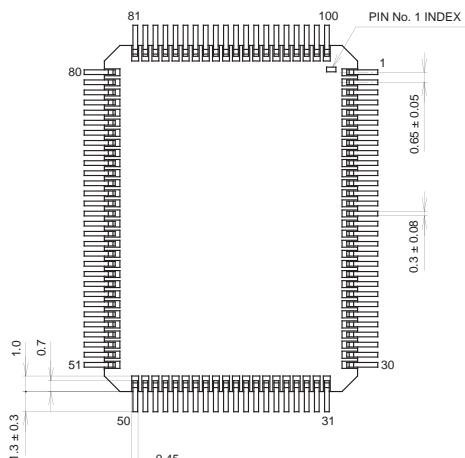
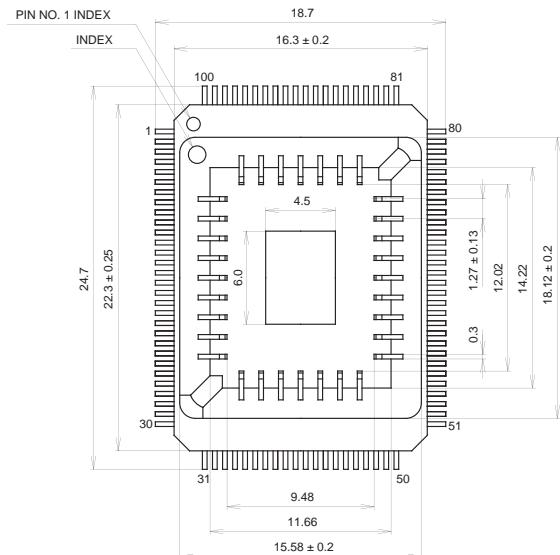
Piggyback mode/evaluator mode can be switched as shown below.



## Package Outline

Unit: mm

100PIN PQFP (CERAMIC)

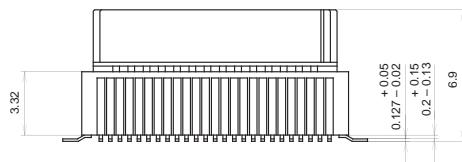
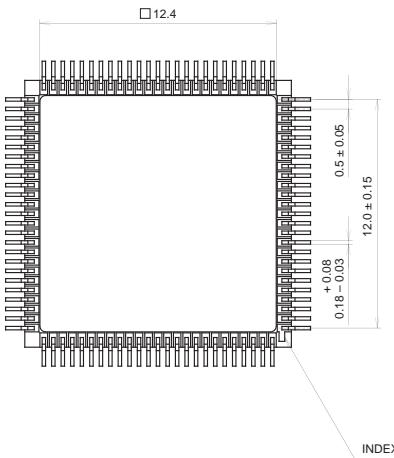
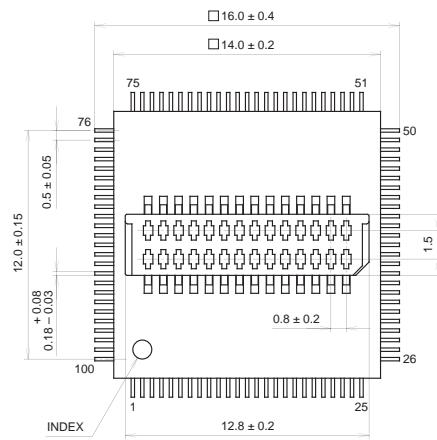


PACKAGE STRUCTURE

SONY CODE	PQFP-100C-L01
EIAJ CODE	AQFP100-C-0000-A
JEDEC CODE	_____

PACKAGE MATERIAL	CERAMIC
LEAD TREATMENT	GOLD PLATING
LEAD MATERIAL	42 ALLOY
PACKAGE WEIGHT	5.7g

100PIN PQFP (CERAMIC)



PACKAGE STRUCTURE

SONY CODE	PQFP-100C-L02
EIAJ CODE	AQFP100-C-1414-A
JEDEC CODE	_____

PACKAGE MATERIAL	CERAMIC
LEAD TREATMENT	GOLD PLATING
LEAD MATERIAL	42 ALLOY
PACKAGE WEIGHT	2.2g